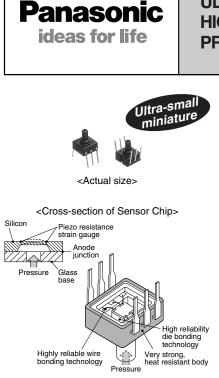
PS (ADP4)



DINO

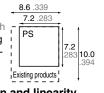
INFORMATION

ULTRA SMALL HIGHLY SEMICONDUCTOR PRESSURE SENSOR

FEATURES

- Ultra-miniature size: much more compact than the PF pressure sensors offered in the past
- · Base area:

7.2(W) x 7.2(D) mm .283(W) x .283(D) inch Only 60% in mounting area and 91% in overall height of previous models (PF)



· High-level precision and linearity A high degree of precision and linear detector response have been achieved by applying the semiconductor strain gauge system. Highly reproducible based on repeated pressure.

- Impressive line-up of models
- Taking their place alongside the standard $5k\Omega$ bridge resistance models are those with a $3.3k\Omega$ resistance which is optimally suited to 5V drive circuits.
- · Economy model (no glass base) gives outstanding value for consumer appliances 40 kPa (0.4 kgf/cm²) and 49 kPa (0.5 kgf/cm2) units are also available.

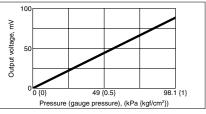
PS PRESSURE SENSOR

• Improved ease of DIP pin insertion into printed circuit boards

The ends of the DIP pins are chamfered to ensure easy insertion into printed circuit boards.

Example of pressure characteristics

(when the rated pressure is between 98.1 kPa (1.0 kgf/cm²)) Drive current: 1.5 mA rated current; ambient temperature: 25°C 77°F



TYPICAL APPLICATIONS

· Medical equipment: Electronic hemodynamometer

- Home appliance: Vacuum cleaner
- Gas equipment: Microprocessor gas
- meter, gas leakage detector • Industrial equipment: Absorption
- device, etc.

ORDERING INFORMATION							
		Ex. ADP					
Part No.		Terminal profile and direction	Rated pressure	Туре	Bridge resistance		
ADP4: PS pressure ser	ensor	1: DIP terminal: Direction opposite the pressure inlet direction 2: DIP terminal: Pressure inlet direction	0: 4.9 kPa {approx. 0.05 kgf/cm²} 1: 14.7 kPa {approx. 0.15 kgf/cm²} 2: 34.3 kPa {approx. 0.35 kgf/cm²} 3: 49.0 kPa {approx. 0.5 kgf/cm²} 4: 98.1 kPa {approx. 0.5 kgf/cm²} 5: 196.1 kPa {approx. 1.0 kgf/cm²} 6: 343.2 kPa {approx. 3.5 kgf/cm²} 7: 490.3 kPa {approx. 5.0 kgf/cm²} 8: 833.6 kPa {approx. 5.0 kgf/cm²} 9: 980.7 kPa {approx. 1.0 kgf/cm²} A: 40.0 kPa {approx. 0.4 kgf/cm²}	1 : Standard type (With glass base) 2: Economy type (Without glass base)	0 : 5.0kΩ 3 : 3.3kΩ		

Bridge resistance		5.0)kΩ	3.3	Packing quantity			
Pressure		rennina	DIP terminal: Direction opposite the pressure inlet direction	DIP terminal: Pressure inlet direction		DIP terminal: Pressure inlet direction	Inner	Outer
	4.9kPa	approx. 0.05kgf/cm ²	ADP41010	ADP42010				
	14.7kPa	approx. 0.15kgf/cm ²	ADP41110	ADP42110				
Standard 49.0kF	34.3kPa	approx. 0.35kgf/cm ² ADP41210		ADP42210				
	49.0kPa	approx. 0.5kgf/cm ²	ADP41310	ADP42310				
	98.1kPa	approx. 1.0kgf/cm ²	ADP41410	ADP42410	ADP41413	ADP42413		
(With glass	196.1kPa	approx. 2.0kgf/cm ²	ADP41510	ADP42510			100	1,000
base)	343.2kPa	approx. 3.5kgf/cm ²	ADP41610	ADP42610			pcs.	pcs.
	490.3kPa	approx. 5.0kgf/cm ²	ADP41710	ADP42710				
833.6kPa		approx. 8.5kgf/cm ²	ADP41810	ADP42810				
	980.7kPa	approx. 10.0kgf/cm ²	ADP41910	ADP42910	ADP41913	ADP42913		
Economy type	40.0kPa	approx. 0.4kgf/cm ²			ADP41A23	ADP42A23		
(Without glass base)	49.0kPa	approx. 0.5kgf/cm ²	ADP41320	ADP42320				

PS (ADP4)

SPECIFICATIONS

Туре		Standard type (With glass base)									Economy type (Without glass base)				
Type of pressure		Gauge pressure													
Pressure n	nedium						Air (For of	her mediu	m, please co	onsult us.)					
Rated	Unit: kPa	4.9	14.7	34.3	49.0	98.1	196.1	343.2	490.3	833.6	980.7	98.1	980.7	40.0	49.0
pressure	Unit: kgf/cm ² (approx.)	0.05	0.15	0.35	0.5	1.0	2.0	3.5	5.0	8.5	10.0	1.0	10.0	0.4	0.5
Max. applied pressure		Twice the rated pressure 1.5 times Twice the rated pressure rated										1.5 times the rated pressure			
Bridge res	istance	5000±1000 Ω 3300±7									700 Ω	3300±600 Ω	5000±1000 Ω		
Ambient temperature		-20 to 100°C -4 to 212°F (no freezing or condensation)											-20 to +100°C -4 to +212°F		
Storage temperature		-40 to 120°C -40 to 248°F (no freezing or condensation)									-20 to +70°C -4 to +158°F	-40 to +120°C -40 to +248°F			
Temperature compensation range		0 to 50°C 32 to 122°F 0 to 60°C 32 to 140°F										0 to 50°C 32 to 122°F			
Drive current (constant current)		1.5 mA DC 1.0 mA DC										1.5 mA DC			
Output span voltage		40±20 mV 100±40 mV 65±25 mV										43.5±22.5 mV	85±45 mV		
Offset voltage		±20 mV										±15 mV	±25 mV		
Linearity		±0.7%FS	±0.5%FS ±0.3%F			±0.3%FS		±0.5%FS		±0.6	%FS	±1.0%FS		±0.3%FS	
Pressure h	iysteresis	±0.6%FS ±0.4%FS ±0.2%FS ±0.4%FS ±1.0%FS						±0.7	%FS						
	ge-temperature tics (0 to 50°C 32 to 122°F)	±15%FS ±5.0%FS ±3.5%FS									±10%FS	±8%FS			
	temperature tics (0 to 50°C 32 to 122°F)	±10%FS ±2.5%FS									±1.3%FS	±2.5%FS			

Notes) 1. Unless otherwise specified, measurements were taken with a drive current of ±0.01 mA and humidity ranging from 25% to 85%.

2. Please consult us if a pressure medium other than air is to be used.

This is the regulation which applies within the compensation temperature range.
 Please consult us if the intended use involves a negative pressure.

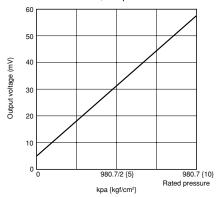
DATA

1. Characteristics data

1-<1> Output characteristics

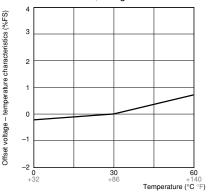
ADP41913

Drive current: 1.0 mA; temperature: 30°C 86°F

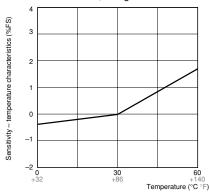


1-<2> Offset voltage - temperature characteristics ADP41913

Drive current: 1.0 mA; rating ±3.5%FS



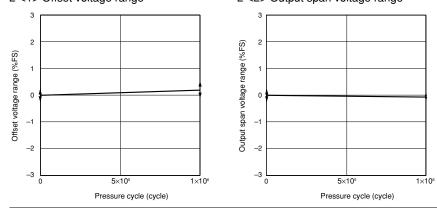
1-<3> Sensitivity - temperature characteristics (%FS) ADP41913 Drive current: 1.0 mA; rating ±2.5%FS



2. Pressure cycle range (0 to rated pressure)

Tested sample: ADP41913, temperature: 100°C 212°F, No. of cycle: 1×10⁶ 2-<1> Offset voltage range

2-<2> Output span voltage range



Even after testing for 1 million times, the variations in the offset voltage and output span voltage are minimal.

PS (ADP4)

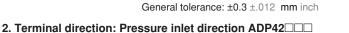
3. Evaluation test

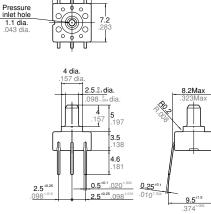
Tested item		Tested condition				
	Storage at high temperature	Temperature: Left in a 120°C 248°F constant temperature bath Time: 1,000 hrs.				
Environmental characteristics	Storage at low temperature	Temperature: Left in a −40°C −40°F constant temperature bath Time: 1,000 hrs.				
	Humidity	Temperature/humidity: Left at 40°C 104°F, 90% RH Time: 1,000 hrs.				
	Temperature cycle	Temperature: -40°C to 120°C -40°F to 248°F 1 cycle: 30 min. Times of cycle: 100	Passed			
Endurance characteristics	High temperature/high humidity operation	Temperature/humidity: 40°C 104°F, 90% RH Operation times: 10 ⁶ , rated voltage applied	Passed			
Mechanical characteristics	Vibration resistance	Double amplitude: 1.5 mm .059 inch Vibration: 10 to 55 Hz Applied vibration direction: X, Y, Z 3 directions Times: 2 hrs each				
	Dropping resistance	Dropping height: 75 cm 29.528 inch Times: 2 times	Passed			
	Terminal strength	Pulling strength: 9.8 N {1 kgf}, 10 sec. Bending strength: 4.9 N {0.5 kgf}, left and right 90° 1 time				
Soldering Resistance	Soldered in DIP soldering bath	Temperature: 230°C 446°F Time: 5 sec.				
	Temperature	Temperature: 260°C 500°F Time: 10 sec.	Passed			

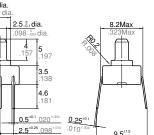
Note: For details other than listed above, please consult us.

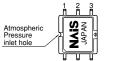
DIMENSIONS

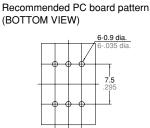
1. Terminal direction: Direction opposite the pressure inlet derection ADP41









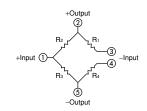


2.5

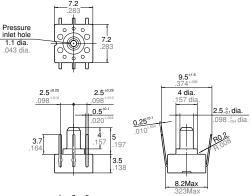
2.5

Tolerance: ±0.1 .004

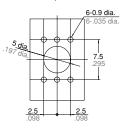
3. Terminal connection diagram



Terminal No.	Name			
1	Power supply (+)			
2	Output (+)			
3	Power supply (-)			
4	Power supply (-)			
5	Output (-)			
6	No connection			
Note: Leave terminal 6 unconnected.				



Recommended PC board pattern (BOTTOM VIEW)



Tolerance: ±0.1 .004

Atmospheric Pressure inlet hole

NOTES

1. Mounting

Use lands on the printed-circuit boards to which the sensor can be securely fixed.

2. Soldering

1) Due to its small size, the thermal capacity of the pressure sensor DIP type is low. Therefore, take steps to minimize the effects of external heat.

Dip soldering bath: Max. 260°C 500°F, 5 sec.

Soldering iron: 260 to 300°C 500 to 572°F (30W) within 5 sec.

2) Use a non-corrosive resin type of flux. Since the pressure sensor DIP type is exposed to the atmosphere, do not allow flux to enter inside.

3. Cleaning

 Since the pressure sensor chip is exposed to the atmosphere, do not allow cleaning fluid to enter inside.
 Avoid ultrasonic cleaning since this may cause breaks or disconnections in

the wiring.

4. Environment

Consult with us before using or storing the pressure sensor chip in a place exposed to corrosive gases (such as the gases given off by organic solvents, sulfites, hydrogen sulfides, etc.) which will adversely affect the performance of the pressure sensor chip.

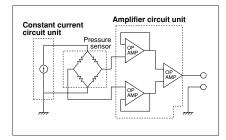
5. Quality check under actual loading conditions

1) To assure reliability, check the sensor under actual loading conditions. Avoid any situation that may adversely affect its performance.

2) As for test data, please contact us.

APPLICATION CIRCUIT DIAGRAM (EXAMPLE)

The pressure sensor is designed to convert a voltage by means of constant current drive and then, if necessary, it amplifies the voltage for use. The circuit shown below is a typical example of a circuit in which the pressure sensor is used.



6. Other handling precautions

1) That using the wrong pressure range or mounting method may result in accidents.

2) Air can be used directly as a pressure medium. Consult with us before using a corrosive gas (such as a gas given off by an organic solvent, sulfite or hydrogen sulfide) as the pressure medium.
3) The pressure sensor chip is positioned inside the pressure inlet. Never poke wires or other foreign matter through the pressure inlet since they may damage the chip or block the inlet. Avoid use when the atmospheric pressure inlet is blocked.

4) Leave pin No. 6 unconnected since the pressure sensor chip may be damaged if a voltage is applied to this pin.
5) Use an operating pressure which is within the rated pressure range. Using a pressure beyond this range may cause damage.

6) Since this pressure sensor chip does not have a water-proof construction, consult with us if it is to be used in a location where it may be sprayed with water, etc.
7) Avoid using the pressure sensor chip in an environment where condensation may form. Furthermore, its output may fluctuate if any moisture adhering to it freezes.

8) The pressure sensor chip is constructed in such a way that its output will fluctuate when it is exposed to light.
Especially when pressure is to be applied by means of a transparent tube, take steps to prevent the pressure sensor chip from being exposed to light.
9) Avoid using the pressure sensor chip where it will be susceptible to ultrasonic or other high-frequency vibration.
10) Since static charge can damage the pressure sensor chip, bear in mind the following handling precautions.

- When storing the pressure sensor chips, use a conductive material to short the pins or wrap the entire chip in aluminum foil. Plastic containers should not be used to store or transport the chips since they readily become charged.
- When using the pressure sensor chips, all the charged articles on the bench surface and the work personnel should be grounded so that any ambient static will be safely discharged.

11) Due to the pressures involved, give due consideration to the securing of the pressure sensor DIP type and to the securing and selection of the inlet tube. Consult us if you have any queries.

MOUNTING METHOD

The general method for transmitting air pressures differs depending on whether the pressure is low or high.

Checkpoints for use

- <1> Select a pressure inlet pipe which is sturdy enough to prevent pressure leaks.
- <2> Fix the pressure inlet pipe securely so as to prevent pressure leaks.
- <3> Do not block the pressure inlet pipe.

Methods of transmitting air pressures

